

## EVG expanding production & test capacity at corporate HQ – August 20, 2021

EV Group – a supplier of wafer bonding and lithography equipment for semiconductor, micro-electro-mechanical systems (MEMS) and [nanotechnology](#) applications – is expanding production capacity at its corporate headquarters in St Florian am Inn, Austria.

Representing a €20m investment, the expansion will include the construction of a new building providing additional production and test capacity for EVG equipment that meets the high cleanliness requirements of the semiconductor industry, as well as allowing for a significant expansion of warehouse space. The new building is set to open by the end of 2017.



Picture: EVG's headquarters, including construction site for additional production and test capacity.

“With the new building adjacent to our existing manufacturing facilities, we will first and foremost create additional test rooms for the final assembly, software installation and quality assurance of our equipment and the technical source inspection by our customers,” says Dr Werner Thallner, executive operations & financial director. “This enables us to act on the significant increase in demand for our solutions in both existing and new markets, and pursue our mid- and long-term growth targets at the same time.”

<https://www.semiconductorforu.com/evg-expanding-production-test-capacity-corporate-hq/>